



**CM50TU-34KA**

**HIGH POWER SWITCHING USE**

**MAXIMUM RATINGS** (T<sub>j</sub> = 25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CE</sub> S	Collector-emitter voltage	G-E Short	1700	V
V <sub>GE</sub> S	Gate-emitter voltage	C-E Short	±20	V
I <sub>C</sub>	Collector current	T <sub>C</sub> = 25°C	50	A
I <sub>CM</sub>		Pulse (Note 2)	100	
I <sub>E</sub> (Note 1)	Emitter current	T <sub>C</sub> = 25°C	50	A
I <sub>EM</sub> (Note 1)		Pulse (Note 2)	100	
P <sub>C</sub> (Note 3)	Maximum collector dissipation	T <sub>C</sub> = 25°C	600	W
T <sub>j</sub>	Junction temperature		-40 ~ +150	°C
T <sub>stg</sub>	Storage temperature		-40 ~ +125	°C
V <sub>iso</sub>	Isolation voltage	Terminals to base plate, f = 60Hz, AC 1 minute	3500	V <sub>rms</sub>
—	Torque strength	Main terminals M5 screw	2.5 ~ 3.5	N • m
		Mounting M5 screw	2.5 ~ 3.5	N • m
—	Weight	Typical value	680	g

**ELECTRICAL CHARACTERISTICS** (T<sub>j</sub> = 25°C, unless otherwise specified)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
I <sub>CES</sub>	Collector cutoff current	V <sub>CE</sub> = V <sub>CE</sub> S, V <sub>GE</sub> = 0V	—	—	1	mA
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	I <sub>C</sub> = 5mA, V <sub>CE</sub> = 10V	4	5.5	7	V
I <sub>GES</sub>	Gate leakage current	±V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V	—	—	0.5	µA
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>C</sub> = 50A, V <sub>GE</sub> = 15V	—	T <sub>j</sub> = 25°C 3.2	4.0	V
		T <sub>j</sub> = 125°C 3.8		—		
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> = 10V V <sub>GE</sub> = 0V	—	—	7.0	nF
C <sub>oes</sub>	Output capacitance		—	—	1.2	
C <sub>res</sub>	Reverse transfer capacitance		—	—	0.38	
Q <sub>G</sub>	Total gate charge	V <sub>CC</sub> = 1000V, I <sub>C</sub> = 50A, V <sub>GE</sub> = 15V	—	225	—	nC
t <sub>d(on)</sub>	Turn-on delay time	V <sub>CC</sub> = 1000V, I <sub>C</sub> = 50A V <sub>GE</sub> = ±15V R <sub>G</sub> = 6.3Ω, Inductive load I <sub>E</sub> = 50A	—	—	100	ns
t <sub>r</sub>	Turn-on rise time		—	—	100	
t <sub>d(off)</sub>	Turn-off delay time		—	—	400	
t <sub>f</sub>	Turn-off fall time		—	—	800	
t <sub>rr</sub> (Note 1)	Reverse recovery time		—	—	200	
Q <sub>rr</sub> (Note 1)	Reverse recovery charge		—	3.9	—	
V <sub>EC</sub> (Note 1)	Emitter-collector voltage	I <sub>E</sub> = 50A, V <sub>GE</sub> = 0V, T <sub>j</sub> = 25°C	—	—	4.6	V
		I <sub>E</sub> = 50A, V <sub>GE</sub> = 0V, T <sub>j</sub> = 125°C	—	2.2	—	V
R <sub>th(j-c)Q</sub>	Thermal resistance*1	IGBT part (1/6 module)	—	—	0.21	K/W
R <sub>th(j-c)R</sub>		FWDi part (1/6 module)	—	—	0.47	
R <sub>th(c-f)</sub>	Contact thermal resistance	Case to heat sink, Thermal compound applied*2 (1/6 module)	—	0.09	—	
R <sub>th(j-c)Q</sub>	Thermal resistance	Case temperature measured point is just under the chips	—	—	0.17*3	

Note 1. I<sub>E</sub>, V<sub>EC</sub>, t<sub>rr</sub>, Q<sub>rr</sub> & die/dt represent characteristics of the anti-parallel, emitter-collector free-wheel diode (FWDi).

2. Pulse width and repetition rate should be such that the device junction temperature (T<sub>j</sub>) does not exceed T<sub>jmax</sub> rating.

3. Junction temperature (T<sub>j</sub>) should not increase beyond 150°C.

4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

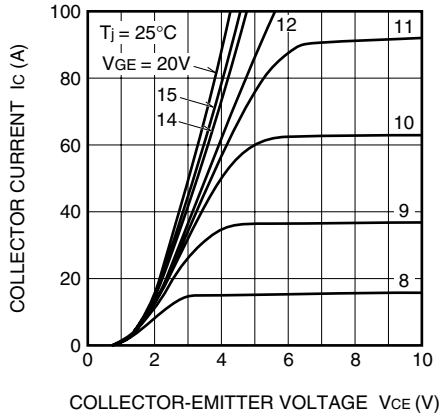
\*1 : Case temperature (T<sub>c</sub>) measured point is indicated in OUTLINE DRAWING.

\*2 : Typical value is measured by using thermally conductive grease of λ = 0.9[W/(m • K)].

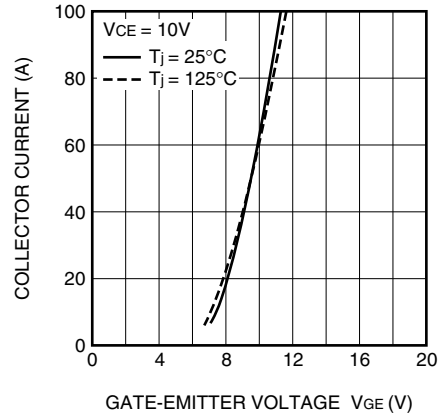
\*3 : If you use this value, R<sub>th(f-a)</sub> should be measured just under the chips.

PERFORMANCE CURVES

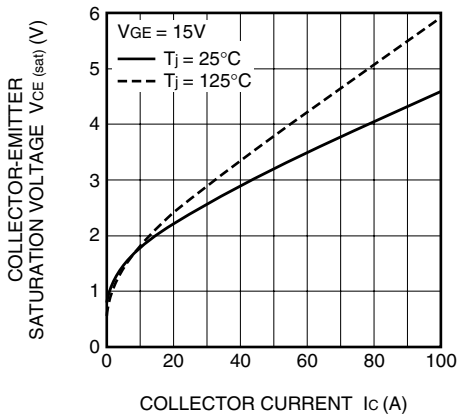
OUTPUT CHARACTERISTICS (TYPICAL)



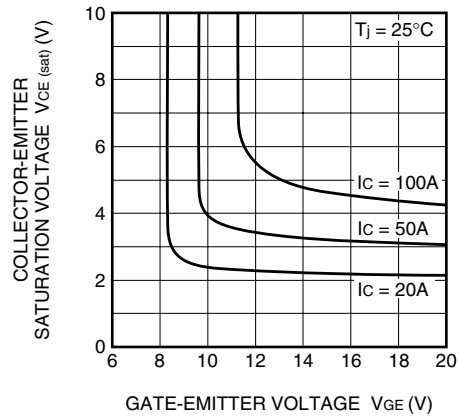
TRANSFER CHARACTERISTICS (TYPICAL)



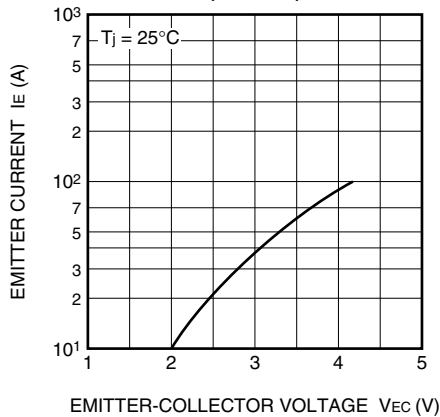
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



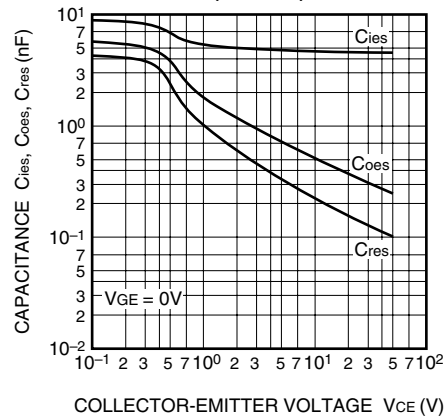
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



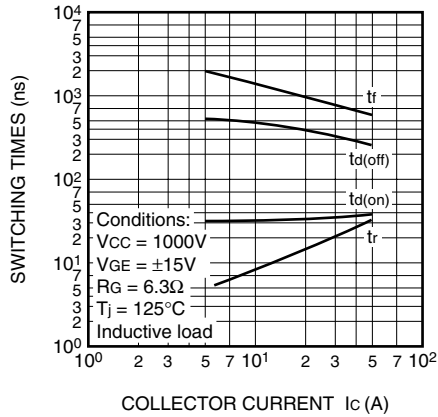
CAPACITANCE-Vce CHARACTERISTICS (TYPICAL)



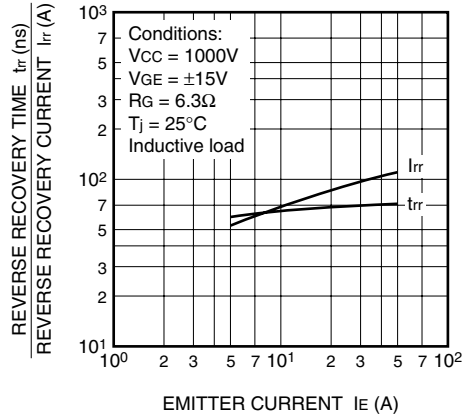
# CM50TU-34KA

## HIGH POWER SWITCHING USE

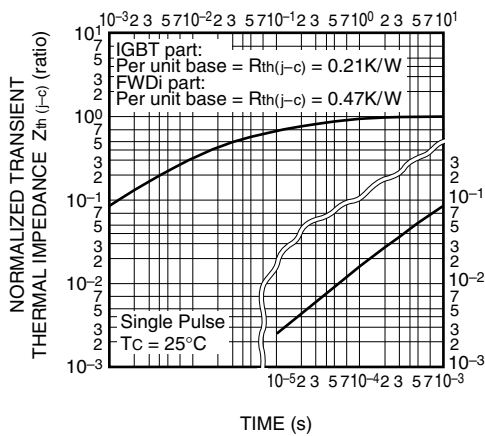
**HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)**



**REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)**



**TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)**



**GATE CHARGE CHARACTERISTICS (TYPICAL)**

